**ADHESIVES**

A COMPREHENSIVE RANGE OF ADHESIVES FOR ELECTRONIC, AUTOMOTIVE AND GENERAL MANUFACTURING INDUSTRIES.

CONSUMABLES

ASSEMBLY MATERIALS AND MACHINE CONSUMABLES USED IN SEMICONDUCTOR, PHOTONIC AND HYBRID ASSEMBLY ETC.

EQUIPMENT

ASSEMBLY, TEST AND INSPECTION EQUIPMENT FOR THE MICROELECTRONIC, ELECTRONIC, PHOTONIC AND SEMICONDUCTOR INDUSTRIES.



inseto

ADVANCED TECHNOLOGY FOR RESEARCH & INDUSTRY

CONNECT NEWSLETTER

Welcome to the twentieth issue of our Company Newsletter "Inseto Connect", dedicated to providing information on new products, supplier & company news and technical announcements.

Inside This Issue:**Page One - Company News:**

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- MPP Purchase K&S MWB Division
- Service Engineer Appointment
- Dual Bond Adhesives Paper
- New Product Presentation Brochure
- Safe Contractor Service Certification

Page Two - Products News:

- Vacuum Soldering Systems
- Flexible Die Bonder Platform
- Die Attach Adhesives
- Package Cover-Lid Assemblies
- Inseto Contact Information

New Employee:

Inseto would like to welcome Adam Marshall to our Technical Support Team. Adam brings a wealth of additional equipment knowledge, having previously worked with a leading power semiconductor manufacturer.

Technical Paper:

Did you see our latest Technical Article on Dual-Curing Adhesives by Eamonn Redmond in a recent issue of the FAST magazine? If not, please contact us for your free copy!

Product Presentation:

Inseto has updated its short-form Product Presentation, download the latest version from our website [HERE!](#)

SÜSS MicroTec Appoints Inseto

Inseto is pleased to announce the signing of an agreement with SÜSS MicroTec to sell their range of process equipment for backend lithography, wafer bonding and photomask processing throughout the UK and Ireland.



Commenting on the agreement, Matthew Brown, Sales Director at Inseto said "We are extremely proud to have secured the agency for SÜSS MicroTec, the developer of the world's first mask aligner and recognised technology leader for backend wafer processing equipment. This appointment not only strengthens our product portfolio in the wafer fabrication sector but also enhances the SÜSS MicroTec presence throughout the UK and Ireland.

MPP Acquire K&S Manual Wire Bonder Division

Micro-Point Pro Ltd. (MPP), founded in 2010 after purchasing the former Kulicke & Soffa (K&S) Micro-Swiss Wedge & Die Attach Tools Division, has now acquired the K&S Manual Wire Bonders Division.

Following relocation of production and support staff as part of the purchase, MPP have committed to a program of continuous improvements to the wire bonder platforms.

In order to provide a continuity of supply for technical support, spare parts and new systems, Inseto has signed an exclusive agreement with MPP to distribute their entire product range throughout the United Kingdom, Ireland and Nordic regions.



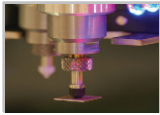
MP Micro Point Pro

Inseto Receives "Safe Contractor" Accreditation

Inseto has recently been awarded "Safe Contractor Accreditation" where the Companies health & safety policy statement, organisation, how we deal with health & safety, in addition to our specific health & safety arrangements were assessed.

The Accreditation ensures that Certified Companies work to an acceptable standard and provides information and assurances to Customers about the health & safety systems and competence of the organisations who have been Safe Contractor accredited.

Further information on the accreditation can be obtained from our Technical Support Department.



Equipment News

CAT - Flexible Die Bonder Platform

The "CAT - Clever Assembly Tool" from Amadyne is a standalone system designed for low-medium volume production of microelectronic and related devices.

Featuring short setup & changeover times, an intuitive graphical user interface for programming and operation and easy integration of customer specific requirements, the CAT is a versatile system for die attach or other assembly processes.

Hardware features include a rugged mineral casting and linear X-Y stage with a 300x400mm working area, in addition to advanced packaging capabilities like automatic tool changeover, dispenser, stamping, eutectic station, chip eject, tape feeders, upward looking vision and inspection options.



ATV – Vacuum Solder Reflow Ovens

ATV's new SRO 714 & 716 models are free-standing Vacuum Solder Reflow Ovens for batch processing with rapid thermal annealing and brazing capability. The systems are ideal for void free soldering of die, sub-mount components or substrates and for package sealing applications.

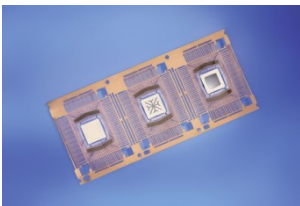
Reflow profiles are created simply using ATV's WIN-ATV software, which allows the user to program up to 100 process steps to create the ideal profile. Options include formic acid processing for flux-free soldering, advanced flux management for solder paste applications, H2/forming gas and Over-Pressure capability, O2 and moisture monitoring etc.

The 714 & 716 systems produce exceptional results, achieving less than 1% temperature variation across their heated area. They are designed for multiple solder reflow processes requiring processing under vacuum, or with process gases & other rapid thermal processes etc.



Adhesives News

Dual Curing Die Attach Adhesives



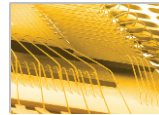
Delo has added a conductive epoxy to its increasingly-larger portfolio of Dual-Curing adhesives. DELO-DUALBOND IC343 is a silver-filled epoxy that cures by a UV/heat combination or just by heat alone.

UV-curing the fillet around the die

immediately after component placement guarantees that movement of the die during the heat-cure stage is eliminated, resulting in improved placement accuracy at a repeatable level.

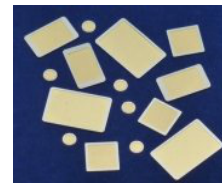
Delo also offers non-conductive epoxies for component-attach where electrical conductivity is not required. DELO-DUALBOND OB749 & OB787 offer the same advantage of the silver-filled epoxy, and also meet the stringent outgassing requirements of both ESA & NASA test methods, ECSS-Q-70 02 & ASTM E 595-93.

Complimenting these die attach materials is a new development adhesive that is thermally conductive but electrically insulating. DELO-DUALBOND VE522912 is a filled with aluminium nitride to enhance its thermal conductivity to 6 W/m-K, and has a measured shear strength of 56N when bonding a 2mm-square die onto gold-plated FR4. It can be cured in 2 seconds, and any shadow zones can be subsequently cured in 5 minutes at 130C.



Materials News

Package Cover Assemblies



Inseto now supplies cover assemblies for hermetic packages. Our supplier, Coining, has invested in a state-of-the art fully automatic robotic handling system that produces superior weld characteristics between the solder preform and the lid,

resulting in consistent, repeatable parts of the highest quality. Lid materials are either metal or customer-supplied ceramic.

See us at the following events:

- Photonics Packaging Conference, 22-23 Nov., Edinburgh
- IMAPS-UK Annual Conference "MicroTech", 16 March 2017, Didcot Nr. Oxford

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